



All for dreams

- 特征 -

1.自动对焦 + 托盘处理程序

- Auto Focus + In-tray handler

2.可对应FCBGA

- Device size:

7mm (W) x 7mm (D)

~ 120mm (W) x 120mm (D)

3.进一步提高生产力

- Further increase productivity

RSH-S80AMPT

新一代IC封装电路板Bump检测装置
IC Substrate 2D/3D Bump Test System



**可支持新一代IC封装电路板3D Bump
高度及外观的同步检测等**

(u-Bump, 圆形, Cu Pillar凸块, 弯曲)

Capable of implementing next-generation IC Substrate 3D Bump inspection.

Apply for Height & Vision inspection simultaneously (u-Bump, Round/Flattened, Warpage)

高速度・高精度检测

- Higher Throughput, Highest accuracy

优化用户界面

- Optimized Interface, Increased Usability

Key Specifications	
2D sensor method	2D CCD Area Camera & Strobe Lighting
3D sensor method	3D Laser Triangulation
Typical Bump Diameter Range (μm)	20-300μm
Typical Bump Height Range (μm)	0-80μm
Min. Bump Pitch (μm)	Synch with Bump height range (50um vs. 50um height)
Min. Bump Gap (μm)	Synch with Bump height range (50um vs. 50um height)
Typical Device size (width)x (Depth) (mm)	7mm (W) x 7mm (D) - 120mm (W) x 120mm (D)
Typical Substrate thickness Range (mm)	0.2mm - 4mm
2D resolution (μm)	X:2.1μm
3D resolution(X,Y) (μm)	X:3.4μm Y:Programmable 1-50μm
3D resolution(Z) (μm) on flat surface	0.08μm
2D accuracy (μm)	1.1μm Diameter
3D accuracy (μm)	3μm Height
Repeatability height (μm)	3σ ≤ 1.5um
Repeatability diameter (μm)	3σ ≤ 2.0um
Repeatability coplanarity (μm)	3σ ≤ 2.0um
Overlap Range (2D, 3D)	Programmable

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*Nidec-Read Corporation to be renamed

Nidec Advance Technology Corporation

from April in 2023.

■Domestic office : Kyoto / Nagoya / Tokyo

■Global office : Taiwan,China / Korea / China / Thai / Canada **More details...**

